

Special Issue

Advances in Bioprinting for Tissue Engineering and Regenerative Medicine

Message from the Guest Editor

Three-dimensional bioprinting has emerged as one of the leading manufacturing platforms for fabrication of highly complex 3D tissues and/or organs. The field of 3D bioprinting has advanced rapidly over the last few years, notably in the advances of bioprinting technologies and the development of novel printable bio-inks and printing strategies. *Applied Sciences*—in which, the title paper “Advances in Bioprinting for Tissue Engineering and Regenerative Medicine” can be found—publishes research that addresses the needs and goals of 3D bioprinting for tissue engineering and regenerative medicine.

Guest Editor

Dr. Wei Long Ng

Singapore Centre for 3D Printing (SC3DP), School of Mechanical and Aerospace Engineering, Nanyang Technological University (NTU), 50 Nanyang Avenue, Singapore 639798, Singapore

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Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
appls@mdpi.com

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

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